

# GL610T

## Ultra-compact Chip Part Type Infrared Emitting Diodes

### ■ Features

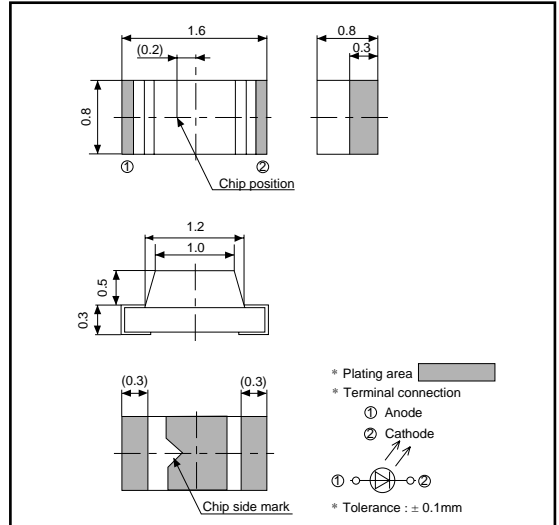
1. Ultra-compact type (1.6 x 0.8 x 0.8 mm)
2. Thin type (thickness : 0.8 mm)
3. Taped-packed type (4,000 pieces/reel)
4. Leadless type

### ■ Applications

1. Compact and thin remote controllers
2. Tape end detection of VCRs and VCR cameras
3. Power source for car navigator touch panels
4. Other portable equipment

### ■ Outline Dimensions

(Unit : mm)



### ■ Absolute Maximum Ratings

(Ta=25°C)

Parameter	Symbol	Rating	Unit
Forward current	$I_F$	50	mA
*1 Peak forward current	$I_{FM}$	500	mA
Reverse voltage	$V_R$	6	V
Power dissipation	P	150	mW
Operating temperature	$T_{opr}$	- 25 to + 85	°C
Storage temperature	$T_{stg}$	- 25 to + 100	°C
*2 Soldering temperature	$T_{sol}$	260	°C

\*1 Pulse width ≤ 100μs, Duty ratio=0.01

\*2 Hand soldering temperature, for MAX. 3 seconds

### ■ Electro-optical Characteristics

(Ta=25°C)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Forward voltage	$V_F$	$I_F = 50\text{mA}$	-	1.3	1.5	V
*1 Peak forward voltage	$V_{FM}$	$I_{FM} = 0.5\text{A}$	-	2.2	3.5	V
Reverse current	$I_R$	$V_R = 3\text{V}$	-	-	10	μA
Radiant flux	$\Phi_e$	$I_F = 20\text{mA}$	0.7	2.0	-	mW
Peak emission wavelength	$\lambda_p$	$I_F = 20\text{mA}$	-	950	-	nm
Half intensity wavelength	$\Delta \lambda$	$I_F = 20\text{mA}$	-	40	-	nm
Response frequency	$f_c$	-	-	300	-	kHz
Half intensity angle	$\Delta \theta$	$I_F = 20\text{mA}$	-	± 60	-	°